



BSI Standards Publication

Semiconductor devices — Micro-electromechanical devices

Part 47: Silicon based MEMS fabrication technology — Measurement method of bending strength of microstructures

National foreword

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The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

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Published by BSI Standards Limited 2024

ISBN 978 0 539 21851 0

ICS 31.080.99

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This British Standard was published under the authority of the Standards Policy and Strategy Committee on 31 August 2024.

Amendments/corrigenda issued since publication

Date	Text affected
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